

Phase 1:
Carrier Assemblies designed to your pin layout arrive at your facility pre-loaded and ready for assembly.



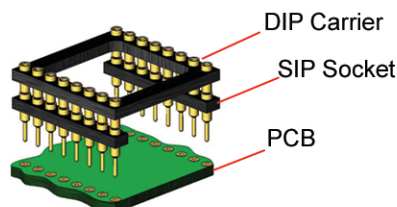
Phase 2:
Carrier Assembly is placed through your soldering process to ensure perpendicularity and coplanarity.



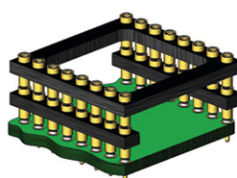
Phase 3:
After soldering, Carrier is removed from the assembly and your device is plugged in.

DIP CARRIER ASSEMBLY

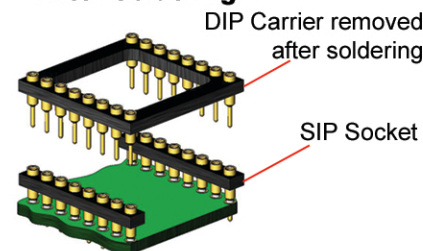
Before Soldering



During Soldering



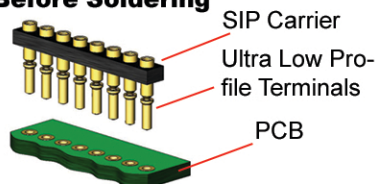
After Soldering



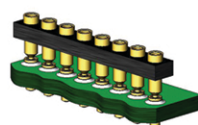
DIP Carrier Assemblies carry two sips through your soldering process to provide a perfectly perpendicular and coplanar socket after soldering. After assembly, DIP carrier is either discarded or sent back to our factory for re-loading.

ULTRA LOW PROFILE SIP CARRIER ASSEMBLY

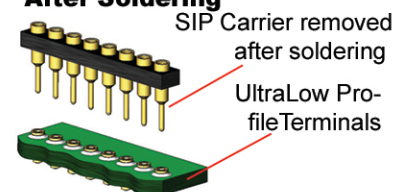
Before Soldering



During Soldering



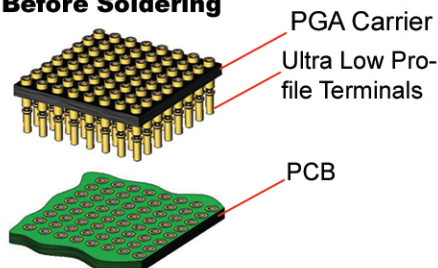
After Soldering



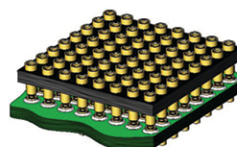
SIP Carrier Assemblies carry low profile terminals through your soldering process to provide a space saving perfectly perpendicular, coplanar, and substrateless socket after soldering. After assembly, SIP carrier is either discarded or sent back to our factory for re-loading.

ULTRA LOW PROFILE PGA CARRIER ASSEMBLY

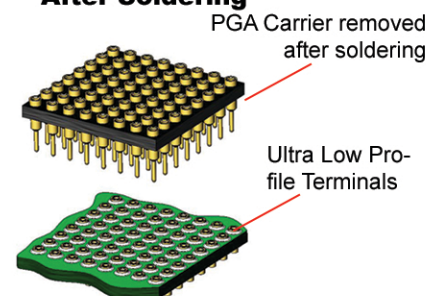
Before Soldering



During Soldering



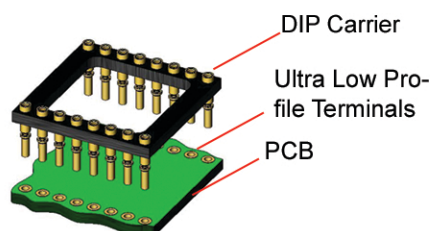
After Soldering



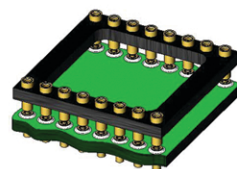
PGA Carrier Assemblies carry low profile terminals through your soldering process to provide a space saving perfectly perpendicular, coplanar, and substrateless socket after soldering. After assembly, the PGA carrier is either discarded or sent back to our factory for re-loading.

ULTRA LOW PROFILE DIP CARRIER ASSEMBLY

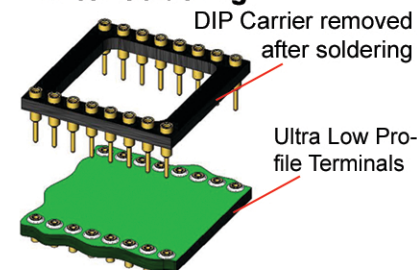
Before Soldering



During Soldering



After Soldering



DIP Carrier Assemblies carry low profile terminals through your soldering process to provide a space saving perfectly perpendicular, coplanar, and substrateless socket after soldering. After assembly, the DIP carrier is either discarded or sent back to our factory for re-loading.

